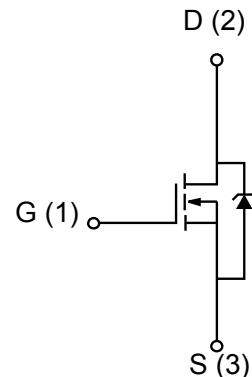


## Description

The MOSFET provide the best combination of fast switching, low on-resistance and cost-effectiveness.

| MOSFET Product Summary |                          |                    |
|------------------------|--------------------------|--------------------|
| V <sub>DS</sub> (V)    | R <sub>DS(on)</sub> (Ω)  | I <sub>D</sub> (A) |
| 650                    | 0.7@V <sub>GS</sub> =10V | 13                 |



## Absolute maximum rating@25°C

| Parameter  | Symbol                             | Maximum   | Units   |
|--|------------------------------------|---|---------|
| Drain-Source Voltage   | V <sub>DS</sub>                    | 650   | V       |
| Gate-Source Voltage  | V <sub>GS</sub>                    | ±30   | V       |
| Continuous Drain Current(T <sub>J</sub> =150°C)  | I <sub>D</sub>                     | 13  | A       |
| T <sub>A</sub> =100°C  |                                    | Figure 3  |         |
| Pulsed Drain Current,V <sub>GS</sub> @10V  | I <sub>DM</sub>                    | Figure 6  | A       |
| Power Dissipation  | P <sub>D</sub>                     | 125   | W       |
| Derating Factor above 25°C   |                                    | 1.0   | w/°C    |
| Peak Diode Recovery dv/dt  | dv/dt                              | 5.0   | V/ns    |
| Single Pulse Avalanche Energy L=11.9mH, I <sub>D</sub> =5.2Amps  | E <sub>AS</sub>                    | 1000  | mJ      |
| Pulsed Avalanche Rating  | I <sub>AS</sub>                    | Figure 8  |         |
| Maximum Temperature for Soldering<br>Leads at 0.063in(1.6mm) from case for 10 seconds<br>Package Body for 10 seconds | T <sub>L</sub><br>T <sub>PKG</sub> | 300   | °C      |
| Operating Junction and Storage Temperature Range   |                                    | 260   |         |
| <b>Thermal Characteristics</b>   |                                    |   |         |
| Parameter  | Symbol                             | Conditions  | Maximum |
| Junction to Ambient  | R <sub>θJA</sub>                   | 1 cubic foot chamber, free air  | 62      |
| Junction to Case   | R <sub>θJC</sub>                   | Water cooled heat sink, P <sub>D</sub> adjusted for a peak junction temperature of +150°C | 1.0     |

## Electrical characteristics per line@25°C( unless otherwise specified)

| Parameter                             | Symbol       | Conditions  | Min. | Typ. | Max.      | Units    |
|---------------------------------------|--------------|---|------|------|-----------|----------|
| Drain-Source Breakdown Voltage        | $BV_{DSS}$   | $I_D = 250\mu A, V_{GS} = 0V$                             | 650  |      | -         | V        |
| Zero Gate Voltage Drain Current       | $I_{DSS}$    | $V_{DS} = 650V, V_{GS} = 0V$                              | -    | -    | 1         | $\mu A$  |
| Gate-Body Leakage Current             | $I_{GSS}$    | $V_{DS} = 0V, V_{GS} = \pm 30V$                           | -    | -    | $\pm 100$ | nA       |
| Gate Threshold Voltage                | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$                         | 2.0  |      | 4.0       | V        |
| Static Drain-Source On-Resistance     | $R_{DS(ON)}$ | $V_{GS} = 10V, I_D = 6.5A$                                | -    | 0.55 | 0.70      | $\Omega$ |
| Drain-Source Diode Forward Voltage    | $V_{SD}$     | $V_{GS} = 0V, I_S = 13A$                                  |      | -    | 1.5       | V        |
| Forward Transconductance              | $g_{fs}$     | $V_{DS} = 30V, I_D = 13A$                                 |      | 19   |           | S        |
| Total Gate Charge                     | $Q_g$        | $V_{GS} = 10V, V_{DD} = 325V, I_D = 13A$                  |      | 46   |           | nC       |
| Gate-Source Charge                    | $Q_{gs}$     |   |      | 10   |           |          |
| Gate-Drain Charge                     | $Q_{gd}$     |   |      | 19   |           |          |
| Turn-On Delay Time                    | $t_{d(on)}$  | $V_{DD} = 325V, V_{GS} = 10V, R_G = 9.1\Omega, I_D = 13A$ | -    | 16   |           | ns       |
| Turn-Off Delay Time                   | $t_{d(off)}$ |   | -    | 29   |           | ns       |
| Turn-On Rise Time                     | $t_r$        |   | -    | 56   |           | ns       |
| Turn-On Fall Time                     | $t_f$        |   | -    | 39   |           | ns       |
| Input Capacitance                     | $C_{iss}$    | $V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$                     |      | 2130 |           | pF       |
| Output Capacitance                    | $C_{oss}$    |   |      | 180  |           | pF       |
| Reverse Transfer Capacitance          | $C_{rss}$    |   |      | 21   |           | pF       |
| Continuous Source Current(Body Diode) | $I_s$        |   |      |      | 13        | A        |
| Maximum Pulsed Current(Body Diode)    | $I_{SM}$     |   |      |      | 52        | A        |
| Reverse Recovery Time                 | $trr$        | $V_{GS} = 0V, I_F = 13A, dI/dt = 100A/\mu s$              |      | 675  |           | ns       |
| Reverse Recovery Charge               | $Q_{rr}$     |   |      | 5.1  |           | $\mu C$  |

## Typical Characteristics

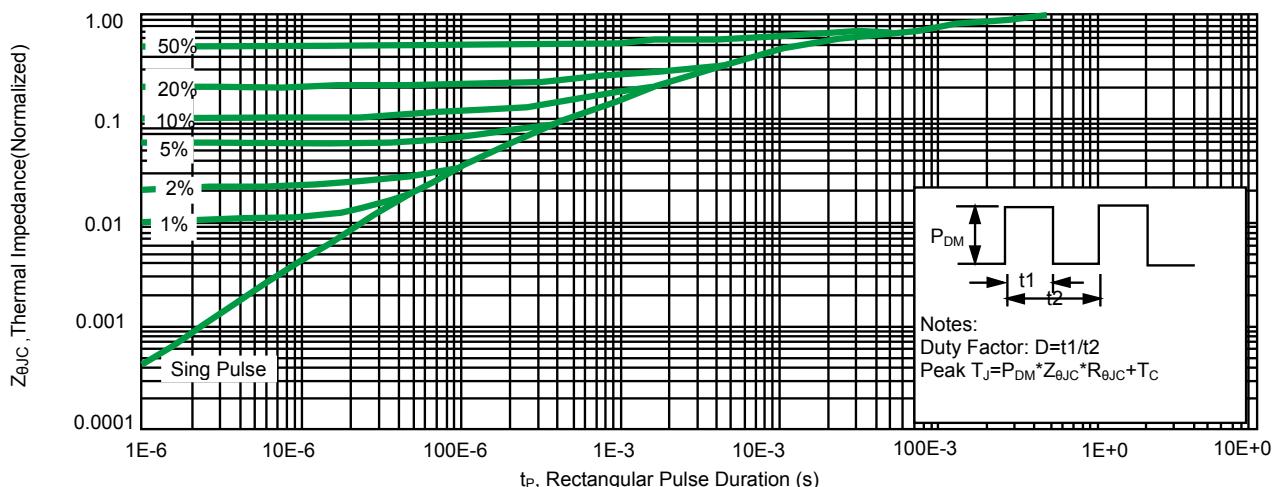


Fig 1. Maximum Effective Thermal Impedance, Junction-to-Case

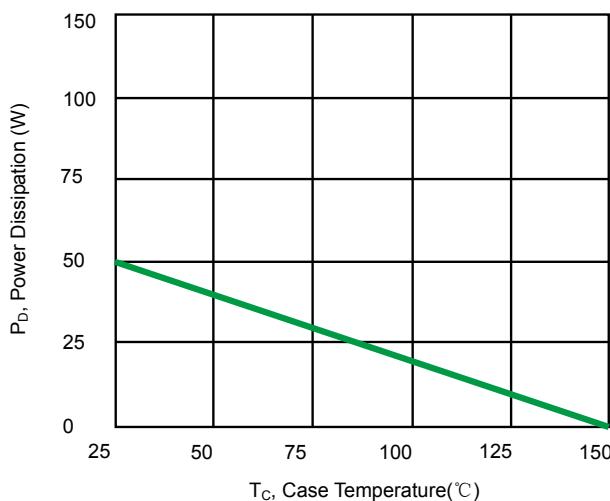


Fig 2. . Maximum Power Dissipation vs. Case Temperature

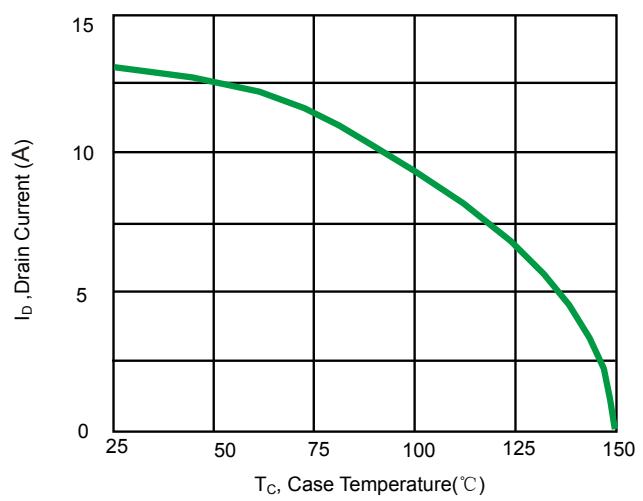


Fig 3. Maximum Continuous Drain Current vs. Case Temperature

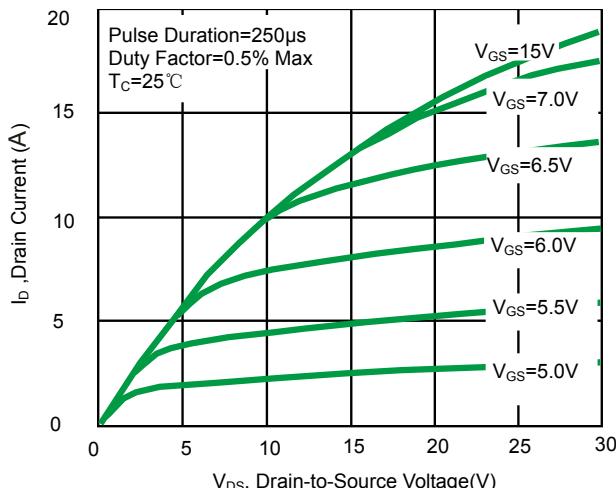


Fig 4. Typical Output Characteristics

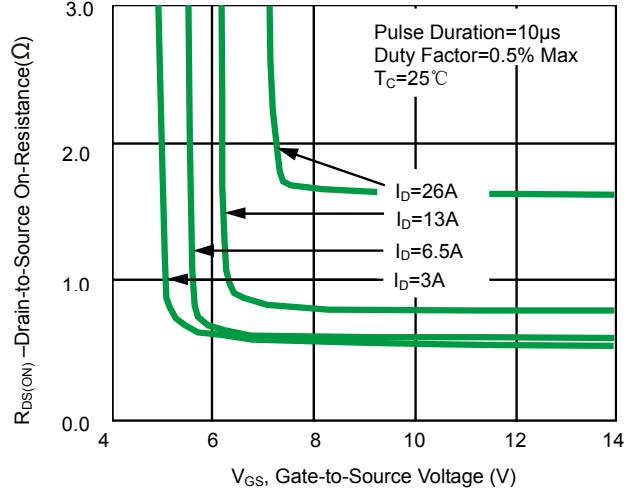


Fig 5. Typical Drain-to-Source ON Resistance vs. Gate Voltage and Drain Current

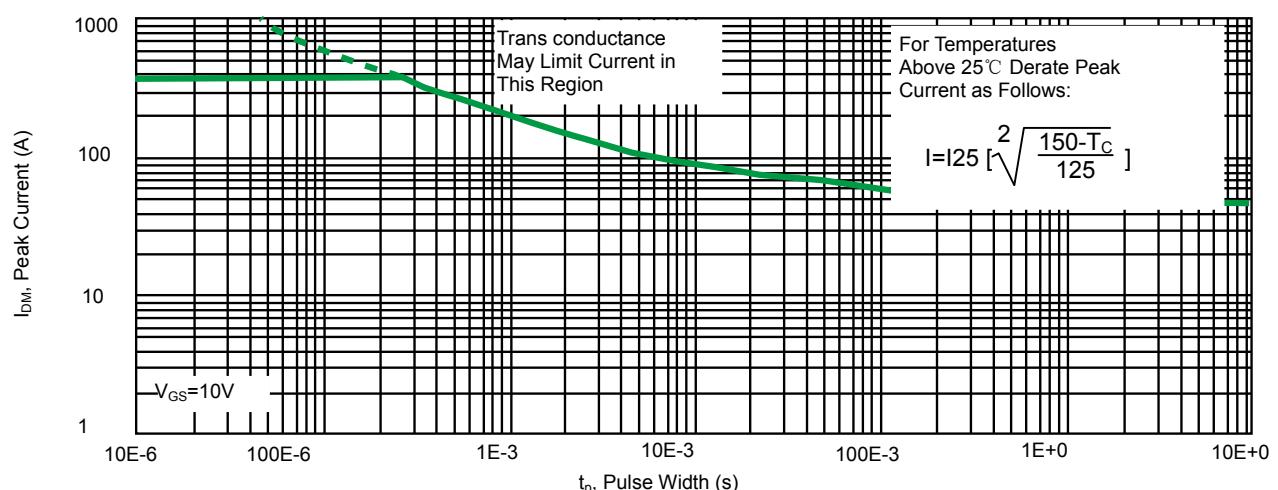


Fig 6. Maximum Peak Current Capability

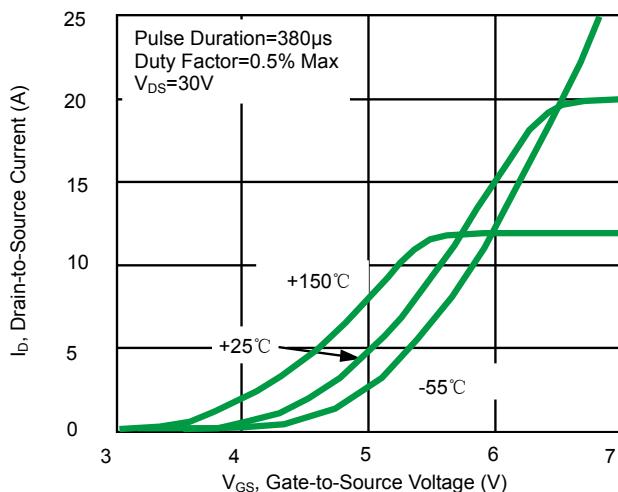


Fig 7. Typical Transfer Characteristics

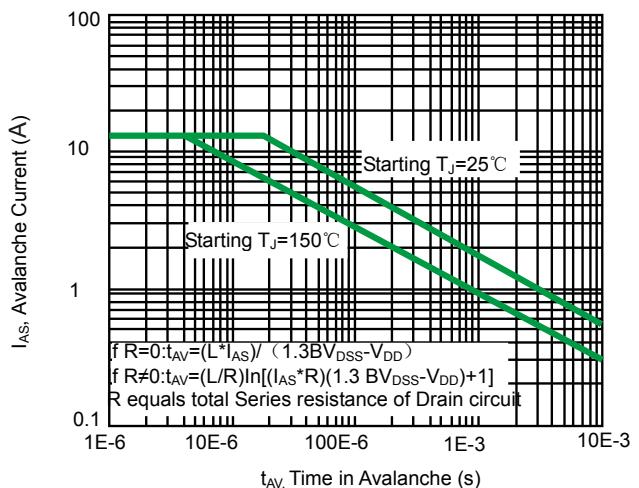


Fig 8. Unclamped Inductive Switching Capability

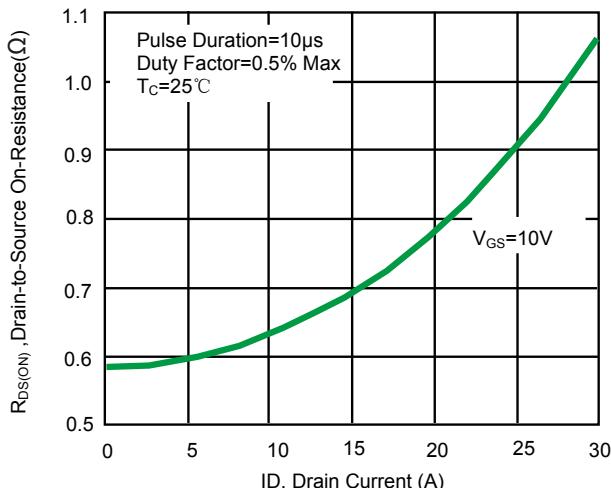


Fig 9. Typical Drain-to-Source ON Resistance vs. Drain Current

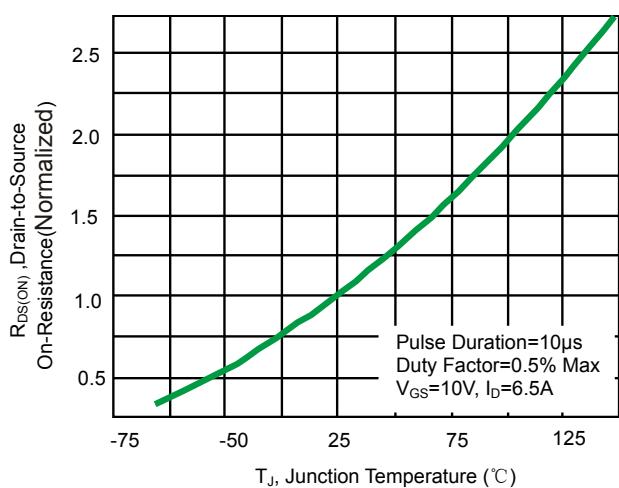


Fig 10. Typical Drain-to-Source ON Resistance vs. Junction Temperature

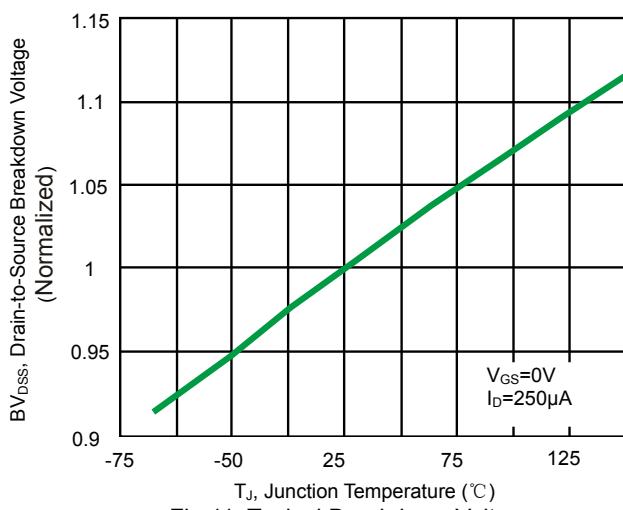


Fig 11. Typical Breakdown Voltage vs. Junction Temperature

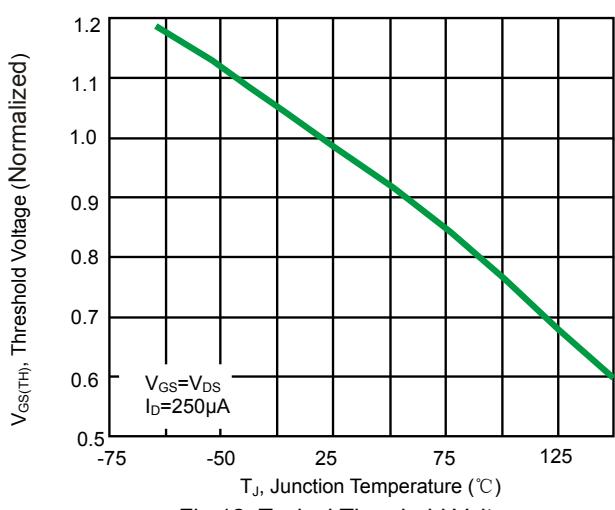


Fig 12. Typical Threshold Voltage vs. Junction Temperature

## N-Channel MOSFET

PNMTOF650V13

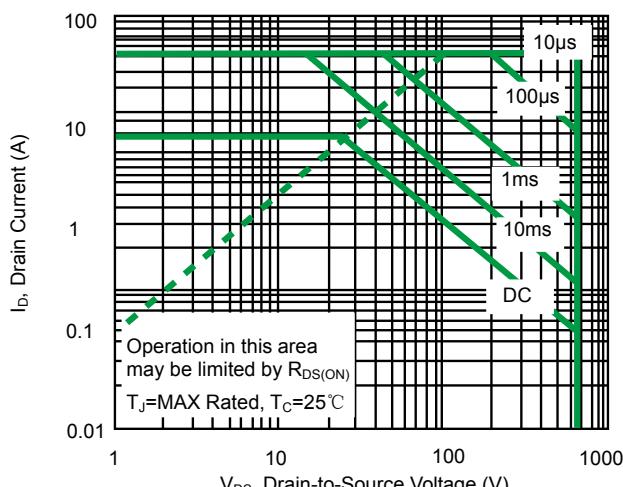


Fig 13. Maximum Forward Bias Safe Operating Area

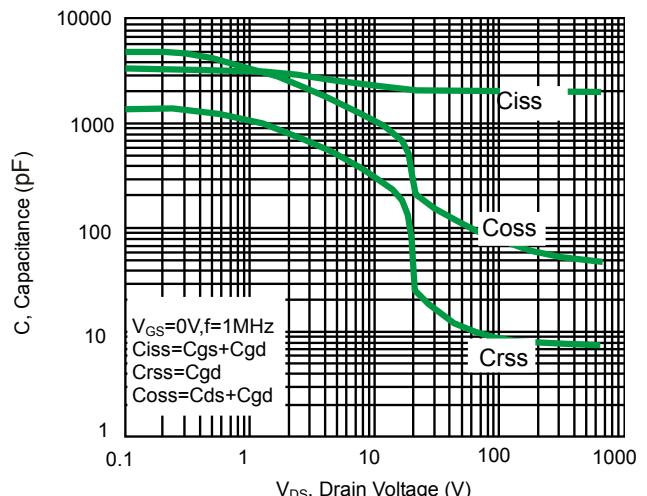


Fig 14. Typical Capacitance vs. Drain Voltage

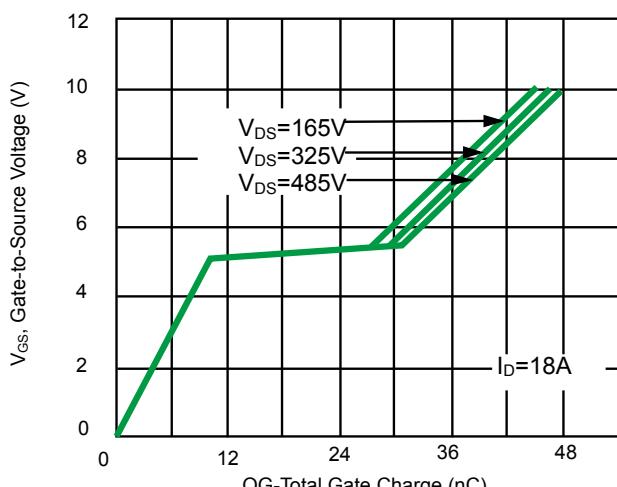


Fig 15. Typical Gate Charge vs. Gate-to-Source Voltage

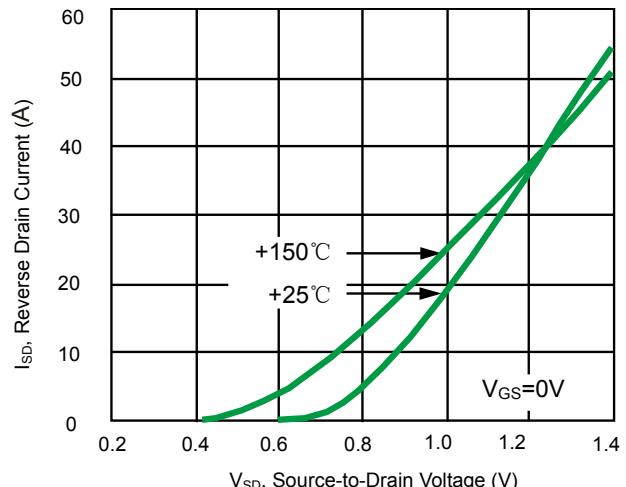


Fig 16. Typical Body Diode Transfer Characteristics

## Test Circuits and Waveforms

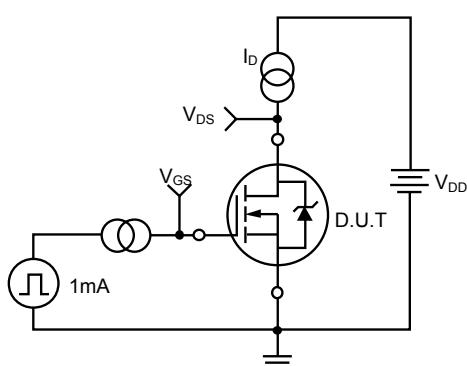


Fig.17 Gate Charge Test Circuit

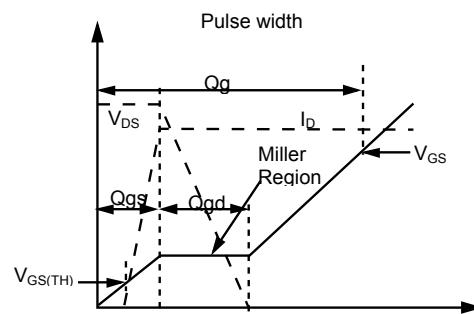


Fig.18 Gate Charge Waveform

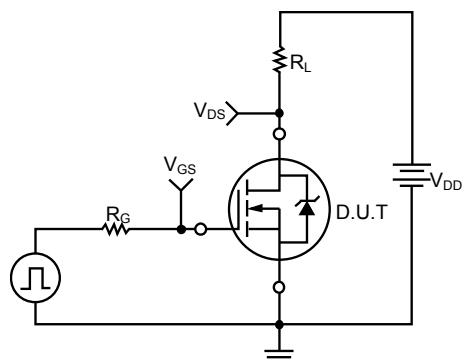


Fig.19 Resistive Switching Test Circuit

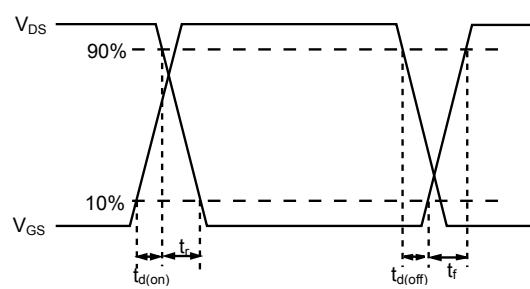


Fig.20 Resistive Switching Waveforms

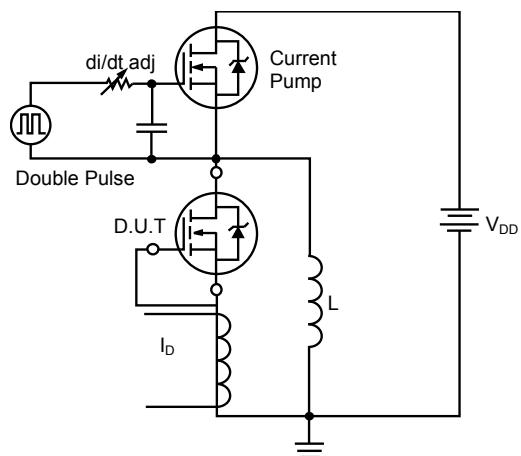


Fig.21 Diode Reverse Recovery Test Circuit

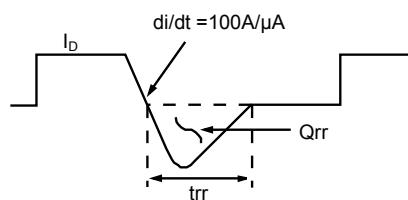


Fig.22 Diode Reverse Recovery Waveform

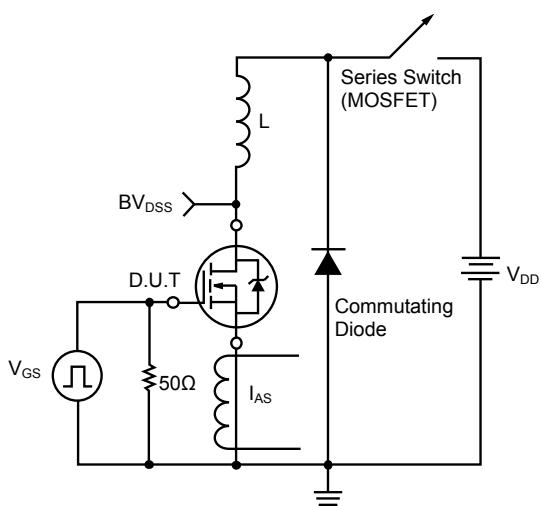


Fig.23 Unclamped Inductive Switching Test Circuit

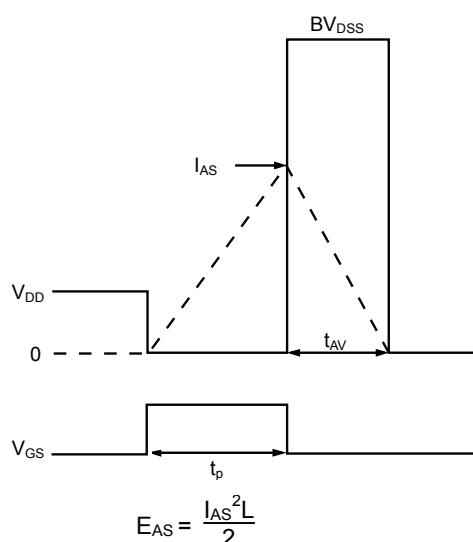
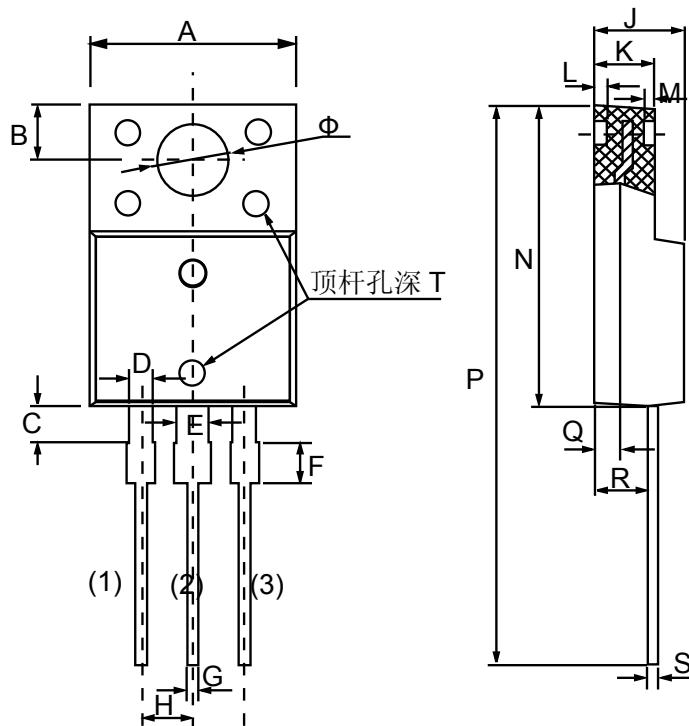


Fig.24 Unclamped Inductive Switching Waveforms

## Product dimension (TO-220F)



| Dim | Millimeters |        | Inches |           |
|-----|-------------|--------|--------|-----------|
|     | MIN         | MAX    | MIN    | MAX       |
| A   | 9.960       | 10.360 | 0.392  | 0.408     |
| B   | 2.700 REF   |        |        | 0.106 REF |
| C   | 1.700       | 1.900  | 0.067  | 0.075     |
| D   | 1.100       | 1.350  | 0.043  | 0.053     |
| E   | 1.500       | 1.750  | 0.059  | 0.069     |
| F   | 1.900       | 2.100  | 0.075  | 0.083     |
| G   | 0.500       | 0.750  | 0.020  | 0.030     |
| H   | 2.540 TYP   |        |        | 0.100 TYP |
| J   | 4.300       | 4.700  | 0.169  | 0.185     |
| K   | 2.800       | 3.200  | 0.110  | 0.126     |
| L   | 0.800 REF   |        |        | 0.031 REF |
| M   | 0.500 REF   |        |        | 0.020 REF |
| N   | 14.800      | 15.200 | 0.583  | 0.598     |
| P   | 28.000      | 28.400 | 1.102  | 1.118     |
| Q   | 1.300 REF   |        |        | 0.051 REF |
| R   | 2.500       | 2.900  | 0.098  | 0.114     |
| S   | 0.500       | 0.750  | 0.020  | 0.030     |
| T   | 0.000       | 0.300  | 0.000  | 0.012     |
| Φ   | 3.500 REF   |        |        | 0.138 REF |

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